WHAT IS CLAIMED IS:

A tray for storing a semiconductor integrated circuit device having a package and wiring terminals on a lower surface of the package, said tray comprising:

a substantially planar main body; and

a first storage portion provided on a first surface of said main body for storing the semiconductor integrated circuit device, said first storage portion having a first wall surface adapted to be arranged around the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said first storage portion,

wherein said first wall surface has a first area which is inclined with an angle so as to support an edge of the package of the semiconductor integrated circuit device and to prevent said first wall surface from coming into contact with the wiring terminals of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said first storage portion.

2. A tray according to claim 1, wherein said first wall surface has a second area extending from said first area in a difection apart from said first surface of said main body, and wherein said second area is inclined with an angle larger than the angle of said first area.

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A tray according to claim 1, wherein said first storage portion is designed so as to prevent said first surface of said main body from coming into contact with the wiring terminals of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said first storage portion.

A tray according to claim 1, wherein said main body includes a plurality of intersecting ridges provided on said first surface thereof, and wherein said first storage portion is defined by a first pair of adjacent ones of said ridges and a second pair of adjacent ones of said ridges extending transversely to said first pair.

S. A tray according to claim \$\nsigma\$, wherein each of said first and second pairs of ridges defining said first storage portion has a wall surface for serving as said first wall surface, whereby said wall surfaces of said first and second pairs of ridges respectively support edges of the lower surface of the rectangular package of the semiconductor integrated circuit device.

5 A tray according to claim 1, further comprising a second storage portion provided on a second surface of said main body opposite to said first storage portion,

wherein said second storage portion can store a

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semiconductor integrated circuit device with wiring terminals thereof facing upward when said tray is turned over, and

wherein when two of said trays are aligned in a stacked relationship, said second storage portion of one tray cooperates with said first storage portion of the other tray to form a space for storing the semiconductor integrated circuit device.

A tray according to claim , wherein said second storage portion has a second wall surface adapted to be arranged around the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said second storage portion with the wiring terminals thereof facing upward, and

wherein said second wall surface has a third area which is inclined with an angle so as to support an edge of the package of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said second storage portion.

A tray according to claim &, further comprising positioning means for positioning said stacked trays to each other.

&. A tray according to claim &, wherein said main body includes a plurality of projecting pieces provided on said second surface thereof for defining

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said second storage portion, and wherein each of said projecting pieces has a wall surface for serving as said second wall surface, whereby said wall surfaces of said projecting pieces respectively support corners of the rectangular package of the semiconductor integrated circuit device.

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